

High-Speed CMOS Logic Octal D-Type Flip-Flop With Data Enable

Features

- Buffered Common Clock
- Buffered Inputs
- Typical Propagation Delay at $C_L = 15\text{pF}$, $V_{CC} = 5\text{V}$, $T_A = 25^\circ\text{C}$
 - 14 ns (HC Types)
 - 16 ns (HCT Types)
- Fanout (Over Temperature Range)
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5\text{V}$
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility, $V_{IL} = 0.8\text{V}$ (Max), $V_{IH} = 2\text{V}$ (Min)
 - CMOS Input Compatibility, $I_I \leq 1\mu\text{A}$ at V_{OL} , V_{OH}

Description

The 'HC377 and 'HCT377 are octal D-type flip-flops with a buffered clock (CP) common to all eight flip-flops. All the flip-flops are loaded simultaneously on the positive edge of the clock (CP) when the Data Enable (\bar{E}) is Low.

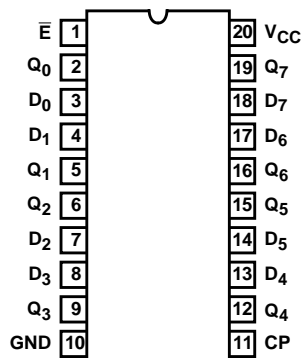
Ordering Information

| PART NUMBER | TEMP. RANGE (°C) | PACKAGE |
|---------------|------------------|--------------|
| CD54HC377F3A | -55 to 125 | 20 Ld CERDIP |
| CD54HCT377F3A | -55 to 125 | 20 Ld CERDIP |
| CD74HC377E | -55 to 125 | 20 Ld PDIP |
| CD74HC377M | -55 to 125 | 20 Ld SOIC |
| CD74HC377M96 | -55 to 125 | 20 Ld SOIC |
| CD74HC377PW | -55 to 125 | 20 Ld TSSOP |
| CD74HC377PWR | -55 to 125 | 20 Ld TSSOP |
| CD74HCT377E | -55 to 125 | 20 Ld PDIP |
| CD74HCT377M | -55 to 125 | 20 Ld SOIC |
| CD74HCT377M96 | -55 to 125 | 20 Ld SOIC |

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel.

Pinout

CD54HC377, CD54HCT377
(CERDIP)
CD74HC377
(PDIP, SOIC, TSSOP)
CD74HCT377
(PDIP, SOIC)
TOP VIEW



Functional Diagram

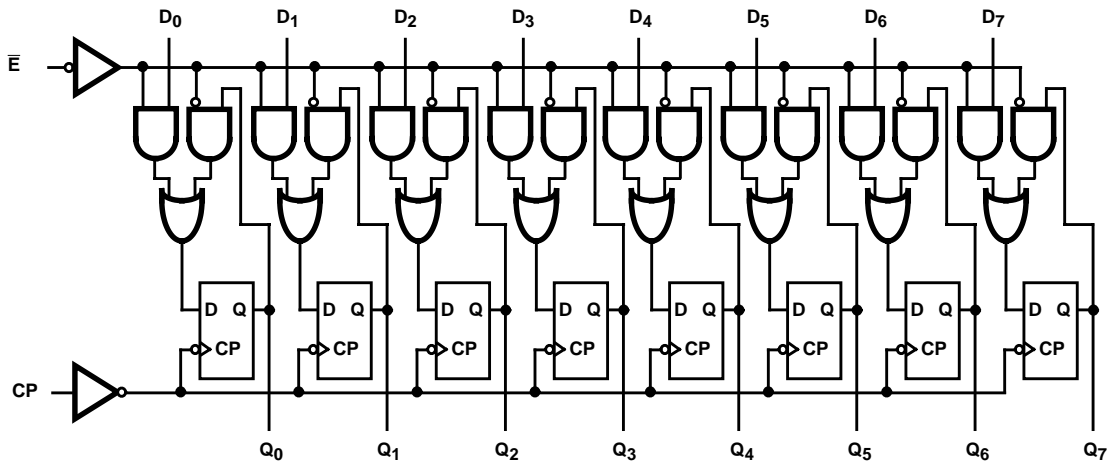


TRUTH TABLE

| OPERATING MODE | INPUTS | | | OUTPUTS |
|-------------------|--------|-----------|-------|-----------|
| | CP | \bar{E} | D_n | Q_n |
| Load "1" | ↑ | l | h | H |
| Load "0" | ↑ | l | l | L |
| Hold (Do Nothing) | ↑ | h | X | No Change |
| | X | H | X | No Change |

H = High Voltage Level Steady State.
 h = High Voltage Level One Set-up Time Prior to the Low to High Clock Transition.
 L = Low Voltage Level Steady State.
 l = Low Voltage Level One Set-up Time Prior to the Low to High Clock Transition.
 X = Don't Care.
 ↑ = Low to High Clock Transition.

Logic Diagram



CD54HC377, CD74HC377, CD54HCT377, CD74HCT377

Absolute Maximum Ratings

| | |
|--|-------------|
| DC Supply Voltage, V_{CC} | -0.5V to 7V |
| DC Input Diode Current, I_{IK} | |
| For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ | $\pm 20mA$ |
| DC Output Diode Current, I_{OK} | |
| For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ | $\pm 20mA$ |
| DC Output Source or Sink Current per Output Pin, I_O | |
| For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ | $\pm 25mA$ |
| DC V_{CC} or Ground Current, I_{CC} or I_{GND} | $\pm 50mA$ |

Thermal Information

| | |
|--|----------------------|
| Thermal Resistance (Typical, Note 1) | θ_{JA} (°C/W) |
| E (PDIP) Package | 69 |
| M (SOIC) Package | 58 |
| PW (TSSOP) Package | 83 |
| Maximum Junction Temperature | 150°C |
| Maximum Storage Temperature Range | -65°C to 150°C |
| Maximum Lead Temperature (Soldering 10s) | 300°C |
| (SOIC - Lead Tips Only) | |

Operating Conditions

| | |
|---|----------------|
| Temperature Range (T_A) | -55°C to 125°C |
| Supply Voltage Range, V_{CC} | |
| HC Types | .2V to 6V |
| HCT Types | .4.5V to 5.5V |
| DC Input or Output Voltage, V_I , V_O | 0V to V_{CC} |
| Input Rise and Fall Time | |
| 2V | 1000ns (Max) |
| 4.5V | 500ns (Max) |
| 6V | 400ns (Max) |

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

| PARAMETER | SYMBOL | TEST CONDITIONS | | V_{CC} (V) | 25°C | | | -40°C TO 85°C | | -55°C TO 125°C | | UNITS |
|---|----------|----------------------|------------|--------------|------|-----|-----------|---------------|---------|----------------|---------|---------|
| | | V_I (V) | I_O (mA) | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| HC TYPES | | | | | | | | | | | | |
| High Level Input Voltage | V_{IH} | - | - | 2 | 1.5 | - | - | 1.5 | - | 1.5 | - | V |
| | | | | 4.5 | 3.15 | - | - | 3.15 | - | 3.15 | - | V |
| | | | | 6 | 4.2 | - | - | 4.2 | - | 4.2 | - | V |
| Low Level Input Voltage | V_{IL} | - | - | 2 | - | - | 0.5 | - | 0.5 | - | 0.5 | V |
| | | | | 4.5 | - | - | 1.35 | - | 1.35 | - | 1.35 | V |
| | | | | 6 | - | - | 1.8 | - | 1.8 | - | 1.8 | V |
| High Level Output Voltage CMOS Loads | V_{OH} | V_{IH} or V_{IL} | -0.02 | 2 | 1.9 | - | - | 1.9 | - | 1.9 | - | V |
| | | | -0.02 | 4.5 | 4.4 | - | - | 4.4 | - | 4.4 | - | V |
| | | | -0.02 | 6 | 5.9 | - | - | 5.9 | - | 5.9 | - | V |
| High Level Output Voltage TTL Loads | V_{OH} | V_{IH} or V_{IL} | - | - | - | - | - | - | - | - | - | V |
| | | | -4 | 4.5 | 3.98 | - | - | 3.84 | - | 3.7 | - | V |
| | | | -5.2 | 6 | 5.48 | - | - | 5.34 | - | 5.2 | - | V |
| Low Level Output Voltage CMOS Loads | V_{OL} | V_{IH} or V_{IL} | 0.02 | 2 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| | | | 0.02 | 4.5 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| | | | 0.02 | 6 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| Low Level Output Voltage TTL Loads | V_{OL} | V_{IH} or V_{IL} | - | - | - | - | - | - | - | - | - | V |
| | | | 4 | 4.5 | - | - | 0.26 | - | 0.33 | - | 0.4 | V |
| | | | 5.2 | 6 | - | - | 0.26 | - | 0.33 | - | 0.4 | V |
| Input Leakage Current | I_I | V_{CC} or GND | - | 6 | - | - | ± 0.1 | - | ± 1 | - | ± 1 | μA |
| Quiescent Device Current | I_{CC} | V_{CC} or GND | 0 | 6 | - | - | 8 | - | 80 | - | 160 | μA |

CD54HC377, CD74HC377, CD54HCT377, CD74HCT377

DC Electrical Specifications (Continued)

| PARAMETER | SYMBOL | TEST CONDITIONS | | V _{CC} (V) | 25°C | | | -40°C TO 85°C | | -55°C TO 125°C | | UNITS |
|--|---------------------------|------------------------------------|---------------------|---------------------|------|-----|------|---------------|------|----------------|-----|-------|
| | | V _I (V) | I _O (mA) | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| HCT TYPES | | | | | | | | | | | | |
| High Level Input Voltage | V _{IH} | - | - | 4.5 to 5.5 | 2 | - | - | 2 | - | 2 | - | V |
| Low Level Input Voltage | V _{IL} | - | - | 4.5 to 5.5 | - | - | 0.8 | - | 0.8 | - | 0.8 | V |
| High Level Output Voltage CMOS Loads | V _{OH} | V _{IH} or V _{IL} | -0.02 | 4.5 | 4.4 | - | - | 4.4 | - | 4.4 | - | V |
| High Level Output Voltage TTL Loads | | | -4 | 4.5 | 3.98 | - | - | 3.84 | - | 3.7 | - | V |
| Low Level Output Voltage CMOS Loads | V _{OL} | V _{IH} or V _{IL} | 0.02 | 4.5 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| Low Level Output Voltage TTL Loads | | | 4 | 4.5 | - | - | 0.26 | - | 0.33 | - | 0.4 | V |
| Input Leakage Current | I _I | V _{CC} and GND | 0 | 5.5 | - | - | ±0.1 | - | ±1 | - | ±1 | μA |
| Quiescent Device Current | I _{CC} | V _{CC} or GND | 0 | 5.5 | - | - | 8 | - | 80 | - | 160 | μA |
| Additional Quiescent Device Current Per Input Pin: 1 Unit Load | ΔI _{CC} (Note 2) | V _{CC} -2.1 | - | 4.5 to 5.5 | - | 100 | 360 | - | 450 | - | 490 | μA |

NOTE:

- For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

| INPUT | UNIT LOADS |
|---------------------------|------------|
| \bar{E} | 1.5 |
| CP | 0.5 |
| All D _n Inputs | 0.25 |

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Table, e.g., 360μA max at 25°C.

Prerequisite for Switching Specifications

| PARAMETER | SYMBOL | TEST CONDITIONS | V _{CC} (V) | 25°C | | | -40°C TO 85°C | | -55°C TO 125°C | | UNITS |
|-------------------------|------------------|-----------------|---------------------|------|-----|-----|---------------|-----|----------------|-----|-------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| HC TYPES | | | | | | | | | | | |
| Maximum Clock Frequency | f _{MAX} | - | 2 | 6 | - | - | 5 | - | 4 | - | MHz |
| | | | 4.5 | 30 | - | - | 25 | - | 20 | - | MHz |
| | | | 6 | 35 | - | - | 29 | - | 23 | - | MHz |
| Clock Pulse Width | t _w | - | 2 | 80 | - | - | 100 | - | 120 | - | ns |
| | | | 4.5 | 16 | - | - | 20 | - | 24 | - | ns |
| | | | 6 | 14 | - | - | 17 | - | 20 | - | ns |

CD54HC377, CD74HC377, CD54HCT377, CD74HCT377

Prerequisite for Switching Specifications (Continued)

| PARAMETER | SYMBOL | TEST CONDITIONS | V _{CC} (V) | 25°C | | | -40°C TO 85°C | | -55°C TO 125°C | | UNITS |
|-------------------------------------|------------------|-----------------|---------------------|------|-----|-----|---------------|-----|----------------|-----|-------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| Set-up Time, \bar{E} , Data to CP | t _{SU} | - | 2 | 60 | - | - | 75 | - | 90 | - | ns |
| | | | 4.5 | 12 | - | - | 15 | - | 18 | - | ns |
| | | | 6 | 10 | - | - | 13 | - | 15 | - | ns |
| Hold Time, Data to CP | t _H | - | 2 | 3 | - | - | 3 | - | 3 | - | ns |
| | | | 4.5 | 3 | - | - | 3 | - | 3 | - | ns |
| | | | 6 | 3 | - | - | 3 | - | 3 | - | ns |
| Hold Time, \bar{E} to CP | t _H | - | 2 | 5 | - | - | 5 | - | 5 | - | ns |
| | | | 4.5 | 5 | - | - | 5 | - | 5 | - | ns |
| | | | 6 | 5 | - | - | 5 | - | 5 | - | ns |
| HCT TYPES | | | | | | | | | | | |
| Maximum Clock Frequency | f _{MAX} | - | 4.5 | 25 | - | - | 20 | - | 16 | - | MHz |
| Clock Pulse Width | t _W | - | 4.5 | 20 | - | - | 25 | - | 30 | - | ns |
| Set-up, Time \bar{E} , Data to CP | t _{SU} | - | 4.5 | 12 | - | - | 15 | - | 18 | - | ns |
| Hold Time, Data to CP | t _H | - | 4.5 | 3 | - | - | 3 | - | 3 | - | ns |
| Hold Time, \bar{E} to CP | t _H | - | 4.5 | 5 | - | - | 5 | - | 5 | - | ns |

Switching Specifications Input t_r, t_f = 6ns

| PARAMETER | SYMBOL | TEST CONDITIONS | V _{CC} (V) | 25°C | | | -40°C TO 85°C | | -55°C TO 125°C | | UNITS |
|--|--|-----------------------|---------------------|------|-----|-----|---------------|-----|----------------|-----|-------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| HC TYPES | | | | | | | | | | | |
| Propagation Delay (Figure 1) CP to Q | t _{PLH} , t _{PHL} | C _L = 50pF | 2 | - | - | 175 | - | 220 | - | 265 | ns |
| | | | 4.5 | - | - | 35 | - | 44 | - | 53 | ns |
| | | C _L = 15pF | 5 | - | 14 | - | - | - | - | - | ns |
| | | C _L = 50pF | 6 | - | - | 30 | - | 37 | - | 45 | ns |
| Output Transition Time (Figure 1) | t _{TLH} , t _{THL} | C _L = 50pF | 2 | - | - | 75 | - | 95 | - | 110 | ns |
| | | | 4.5 | - | - | 15 | - | 19 | - | 22 | ns |
| | | | 6 | - | - | 13 | - | 16 | - | 19 | ns |
| Input Capacitance | C _{IN} | C _L = 50pF | - | - | - | 10 | - | 10 | - | 10 | pF |
| Maximum Clock Frequency | f _{MAX} | C _L = 15pF | 5 | - | 60 | - | - | - | - | - | MHz |
| Power Dissipation Capacitance (Notes 3, 4) | C _{PD} | C _L = 15pF | 5 | - | 31 | - | - | - | - | - | pF |
| HCT TYPES | | | | | | | | | | | |
| Propagation Delay (Figure 1) CP to Q | t _{PLH} , t _{PHL} | C _L = 50pF | 4.5 | - | - | 38 | - | 48 | - | 57 | ns |
| | | C _L = 15pF | 5 | - | 16 | - | - | - | - | - | ns |
| Output Transition Time (Figure 1) | t _{TLH} , t _{THL} | C _L = 50pF | 4.5 | - | - | 15 | - | 19 | - | 22 | ns |
| Input Capacitance | C _{IN} | C _L = 50pF | - | - | - | 10 | - | 10 | - | 10 | pF |

CD54HC377, CD74HC377, CD54HCT377, CD74HCT377

Switching Specifications Input t_r , $t_f = 6\text{ns}$ (Continued)

| PARAMETER | SYMBOL | TEST CONDITIONS | V_{CC} (V) | 25°C | | | -40°C TO 85°C | | -55°C TO 125°C | | UNITS |
|--|-----------|---------------------|--------------|------|-----|-----|---------------|-----|----------------|-----|-------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| Maximum Clock Frequency | f_{MAX} | $C_L = 15\text{pF}$ | 5 | - | 50 | - | - | - | - | - | MHz |
| Power Dissipation Capacitance (Notes 3, 4) | C_{PD} | $C_L = 15\text{pF}$ | 5 | - | 35 | - | - | - | - | - | pF |

NOTES:

3. C_{PD} is used to determine the dynamic power consumption, per flip-flop.
4. $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ where f_i = Input Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuits and Waveforms



FIGURE 1. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

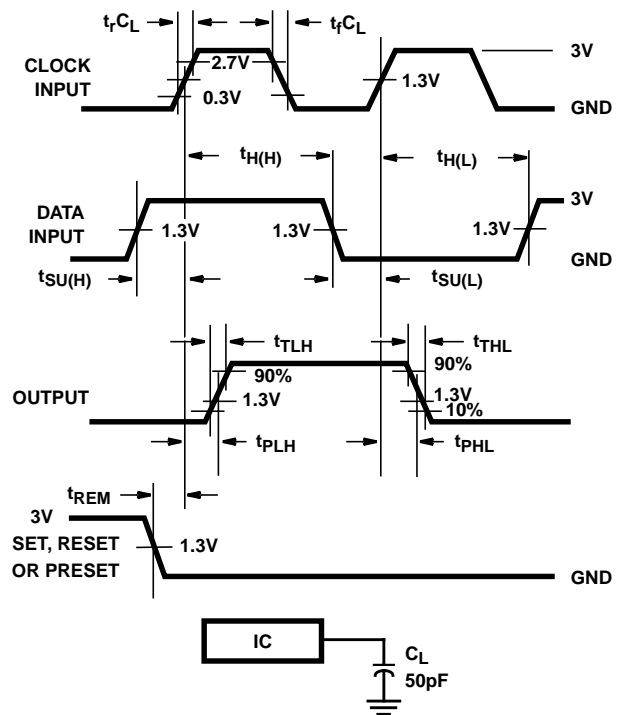


FIGURE 2. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|------------------|--------------------------------------|----------------------|--------------|---------------------------------|-------------------------|
| 5962-8976901RA | ACTIVE | CDIP | J | 20 | 20 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8976901RA CD54HCT377F3A | Samples |
| CD54HC377F3A | ACTIVE | CDIP | J | 20 | 20 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8780701RA CD54HC377F3A | Samples |
| CD54HCT377F3A | ACTIVE | CDIP | J | 20 | 20 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8976901RA CD54HCT377F3A | Samples |
| CD74HC377E | ACTIVE | PDIP | N | 20 | 20 | RoHS & Non-Green | NIPDAU | N / A for Pkg Type | -55 to 125 | CD74HC377E | Samples |
| CD74HC377M | LIFEBUY | SOIC | DW | 20 | 25 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC377M | |
| CD74HC377M96 | ACTIVE | SOIC | DW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC377M | Samples |
| CD74HC377PWR | ACTIVE | TSSOP | PW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HJ377 | Samples |
| CD74HCT377E | ACTIVE | PDIP | N | 20 | 20 | RoHS & Non-Green | NIPDAU | N / A for Pkg Type | -55 to 125 | CD74HCT377E | Samples |
| CD74HCT377M | LIFEBUY | SOIC | DW | 20 | 25 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HCT377M | |
| CD74HCT377M96 | ACTIVE | SOIC | DW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HCT377M | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD54HC377, CD54HCT377, CD74HC377, CD74HCT377 :

● Catalog : [CD74HC377](#), [CD74HCT377](#)

● Military : [CD54HC377](#), [CD54HCT377](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD74HC377M96 | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.3 | 2.7 | 12.0 | 24.0 | Q1 |
| CD74HC377PWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| CD74HC377PWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.0 | 1.4 | 8.0 | 16.0 | Q1 |
| CD74HCT377M96 | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.3 | 2.7 | 12.0 | 24.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD74HC377M96 | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| CD74HC377PWR | TSSOP | PW | 20 | 2000 | 356.0 | 356.0 | 35.0 |
| CD74HC377PWR | TSSOP | PW | 20 | 2000 | 356.0 | 356.0 | 35.0 |
| CD74HCT377M96 | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |

TUBE


*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|-------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| CD74HC377E | N | PDIP | 20 | 20 | 506 | 13.97 | 11230 | 4.32 |
| CD74HC377M | DW | SOIC | 20 | 25 | 507 | 12.83 | 5080 | 6.6 |
| CD74HCT377E | N | PDIP | 20 | 20 | 506 | 13.97 | 11230 | 4.32 |
| CD74HCT377M | DW | SOIC | 20 | 25 | 507 | 12.83 | 5080 | 6.6 |

PW0020A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220206/A 02/2017

NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

NOTES:

- All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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